Mirror Mezz 15 x 11 OCP Connectors

Footprint-compatible, hermaphroditic Mirror Mezz 15x11 OCP Connector lowers application costs with stackable mating that supports data speeds up to 56 Gbps per differential pair, for telecommunications, networking and other applications.

Features and Advantages

Robust shrouded housing design
Encapsulates the pin field, protecting the pins and offering blind-mate guidance to eliminate any possibility of mis-mating.

Contact beam structure of a mated combination
Prevents vibrations and terminal lift to ensure a constant 2-points of contact for electrical reliability. Beam geometry offers reliable normal force for harsh environments and 1.50mm of nominal contact wipe to ensure sufficient engagement.

Flex cable links
- Offer cost savings and excellent SI with controlled channels and pinned grounds
- Enable relaxed tolerancing for offsets between boards and flexible architectures

Using two 5.00mm stack height Mirror Mezz Connectors with 10.00mm flex provides 20.00 to 120.00mm stack heights.

Wide ground pins
Balance the electrical field and shield the differential pair from surrounding transmission lines.

2 electrically tuned signal contacts
Cleanly transmit high-speed signals for maximum signal integrity surrounding transmission lines.

Precise arranged combination of signals and grounds
Maximizes high-speed performance and clean routing out of the connector footprint, with precisely arranged and populated pin field transmission lines.

Different paddle-to-contact bend direction between the rows
Minimizes the cross-talk between rows.

Stitched BGA design
Offers greater cost savings than insert-molded BGA attachments. Stitched contact structure reduces lead times and the connector design simplifies product matrix.

Intricate terminal structure design
Provides numerous mechanical strengths while also benefiting from cutting-edge electrical features, for some of the fastest speeds in the industry.

Top-side perspectives of Mirror Mezz Connector.

Solution cost vs. cable length

- Connectors
- Assembled Flex
- HD Cable (10 Gb/s)
Mirror Mezz 15 x 11
OCP Connectors

Markets and Applications

Data/Computing
  Servers
  Networking
  Storage

Telecommunications/Networking
  Infrastructure
  Networking

Specifications

REFERENCE INFORMATION
Packaging: Tape and Reel
Mates With: 2.50 and 5.50mm height connectors can self- or cross-mate
Designed In: Millimeters
RoHS: Yes
Halogen Free: Yes
Glow Wire Compliant: NA

ELECTRICAL
Voltage (max.): 30V AC
Current (max.): 1.0A per contact
Low Level Contact Resistance (max. initial):
  30 milliohm for 5mm stack height
Dielectric Withstanding Voltage: 500V DC
Insulation Resistance: 1000 Megohms
Impedance: 90 Ohms

MECHANICAL
Average Mating Force (max.): 0.35N per pin
Unmating Force (min.): 0.045N per pin
Contact Normal Force (min.): 0.2N per pin
Durability (max.): 100 cycles

PHYSICAL
Housing: High Temperature Thermoplastic, UL94-V0
Contact: High Performance Copper Alloy
Plating: Selective Gold
Contact Area — 0.76 micron Gold (Au)
Solder Tail Area — 2.54 micron Tin (Sn)
Underplating — 1.27 micron Nickel (Ni)
Operating Temperature: -55 to +105°C

www.molex.com/link/mirrormezz.html

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